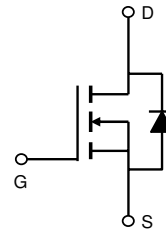
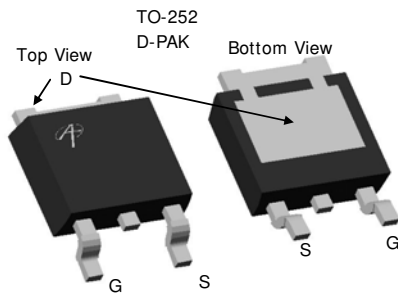


AOD452
N-Channel Enhancement Mode Field Effect Transistor
General Description

The AOD452 uses advanced trench technology and design to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use in PWM, load switching and general purpose applications.

Features

- V_{DS} (V) =25V
- I_D = 55 A (V_{GS} = 10V)
- $R_{DS(ON)} < 8.5 \text{ m}\Omega$ (V_{GS} = 10V)
- $R_{DS(ON)} < 14 \text{ m}\Omega$ (V_{GS} = 4.5V)
- 100% UIS tested
- 100% R_g tested


Absolute Maximum Ratings $T_A=25^\circ\text{C}$ unless otherwise noted

Parameter	Symbol	Maximum	Units
Drain-Source Voltage	V_{DS}	25	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ^G	$T_C=25^\circ\text{C}$	55	A
	$T_C=100^\circ\text{C}$	43	
Pulsed Drain Current ^C	I_{DM}	150	
Pulsed Forward Diode Current ^C	I_{SM}	150	
Avalanche Current ^C	I_{AR}	35	
Repetitive avalanche energy $L=0.1\text{mH}$ ^C	E_{AR}	61	mJ
Power Dissipation ^B	$T_C=25^\circ\text{C}$	51.5	W
	$T_C=100^\circ\text{C}$	25.5	
Power Dissipation ^A	$T_A=25^\circ\text{C}$	2.5	W
	$T_A=70^\circ\text{C}$	1.6	
Junction and Storage Temperature Range	T_J, T_{STG}	-55 to 175	$^\circ\text{C}$

Thermal Characteristics

Parameter	Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$R_{\theta JA}$	14.2	20	$^\circ\text{C/W}$
Maximum Junction-to-Ambient ^A				
Maximum Junction-to-Case ^B	$R_{\theta JC}$	2.4	2.9	$^\circ\text{C/W}$
Maximum Junction-to-TAB ^B	$R_{\theta JC-TAB}$	2.7	3.2	$^\circ\text{C/W}$

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D=250\mu\text{A}$, $V_{GS}=0\text{V}$	25			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS}=20\text{V}$, $V_{GS}=0\text{V}$ $T_J=55^\circ\text{C}$			1 5	μA
I_{GSS}	Gate-Body leakage current	$V_{DS}=0\text{V}$, $V_{GS}=\pm 20\text{V}$			100	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS}=V_{GS}$, $I_D=250\mu\text{A}$	1.2	1.8	3	V
$I_{D(ON)}$	On state drain current	$V_{GS}=10\text{V}$, $V_{DS}=5\text{V}$	100			A
$R_{DS(ON)}$	Static Drain-Source On-Resistance	$V_{GS}=10\text{V}$, $I_D=30\text{A}$		6.5	8.5	m Ω
		$T_J=125^\circ\text{C}$		9.7	12	
		$V_{GS}=4.5\text{V}$, $I_D=20\text{A}$		11.5	14	m Ω
g_{FS}	Forward Transconductance	$V_{DS}=5\text{V}$, $I_D=10\text{A}$		35		S
V_{SD}	Diode Forward Voltage	$I_S=1\text{A}$, $V_{GS}=0\text{V}$		0.72	1	V
I_S	Maximum Body-Diode Continuous Current				55	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}$, $V_{DS}=12.5\text{V}$, $f=1\text{MHz}$		1230	1476	pF
C_{oss}	Output Capacitance			315	400	pF
C_{rss}	Reverse Transfer Capacitance			190	280	pF
R_g	Gate resistance	$V_{GS}=0\text{V}$, $V_{DS}=0\text{V}$, $f=1\text{MHz}$		1.2	2	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=10\text{V}$, $V_{DS}=12.5\text{V}$, $I_D=20\text{A}$		26.4	32	nC
$Q_g(4.5\text{V})$	Total Gate Charge			13.5	17	nC
Q_{gs}	Gate Source Charge			3.9	5	nC
$Q_{gs(Vth)}$	Gate Source Charge at V_{th}			1.3	2	nC
Q_{gd}	Gate Drain Charge			7.8	10	nC
$t_{D(on)}$	Turn-On DelayTime			6.5	8	ns
t_r	Turn-On Rise Time	$V_{GS}=10\text{V}$, $V_{DS}=12.5\text{V}$, $R_L=0.6\Omega$, $R_{GEN}=3\Omega$		10	20	ns
$t_{D(off)}$	Turn-Off DelayTime			22.7	30	ns
t_f	Turn-Off Fall Time			6.2	12	ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		23.1	28	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=20\text{A}$, $dI/dt=100\text{A}/\mu\text{s}$		15.3	18	nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The Power dissipation P_{DSM} is based on $R_{\theta JA}$ and the maximum allowed junction temperature of 150°C . The value in any given application depends on the user's specific board design, and the maximum temperature of 175°C may be used if the PCB allows it.

B: The power dissipation P_D is based on $T_{J(MAX)}=175^\circ\text{C}$, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heatsinking is used.

C: Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}=175^\circ\text{C}$.

D: The $R_{\theta JA}$ is the sum of the thermal impedance from junction to case $R_{\theta JC}$ and case to ambient.

E: The static characteristics in Figures 1 to 6 are obtained using $<300 \mu\text{s}$ pulses, duty cycle 0.5% max.

F: These curves are based on the junction-to-case thermal impedance which is measured with the device mounted to a large heatsink, assuming a maximum junction temperature of $T_{J(MAX)}=175^\circ\text{C}$.

G: The maximum current rating is limited by bond-wires.

H: These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

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TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

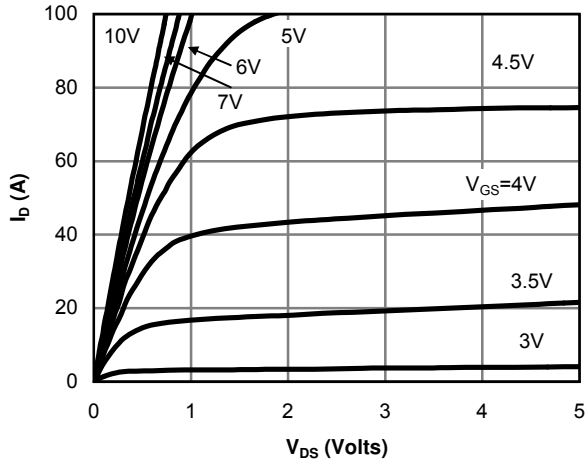


Fig 1: On-Region Characteristics

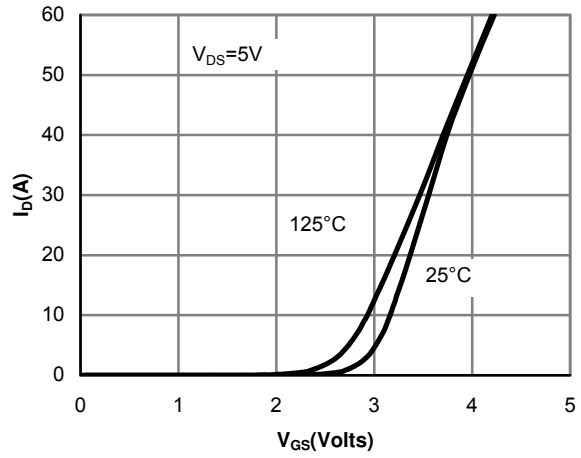


Figure 2: Transfer Characteristics

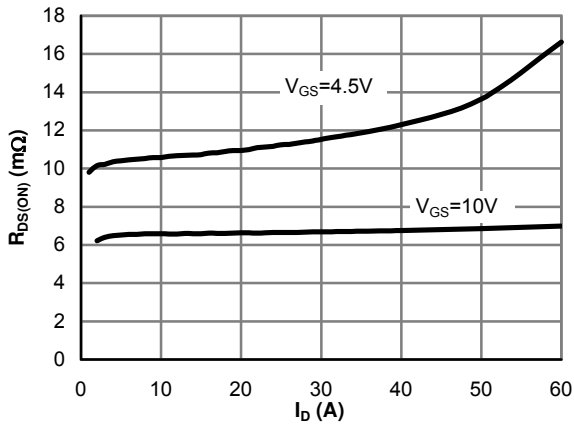


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

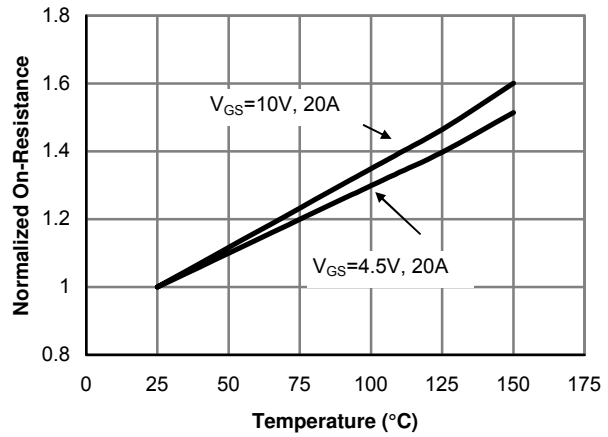


Figure 4: On-Resistance vs. Junction Temperature

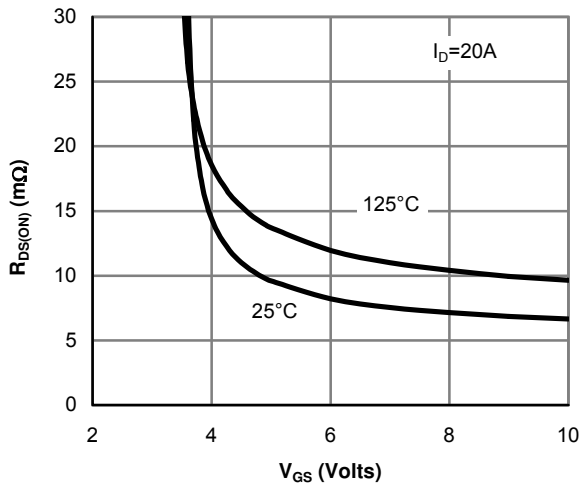


Figure 5: On-Resistance vs. Gate-Source Voltage

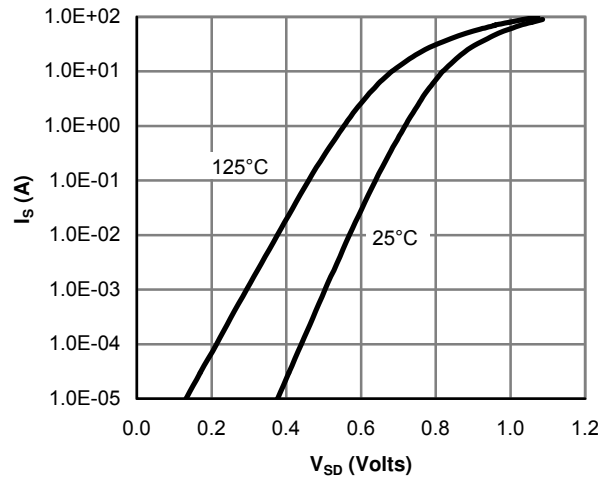


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

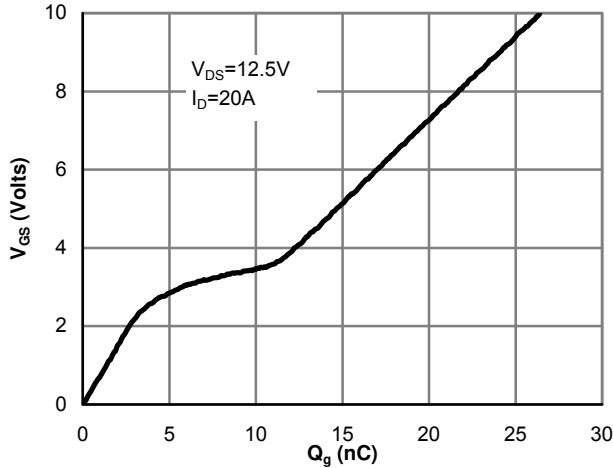


Figure 7: Gate-Charge Characteristics

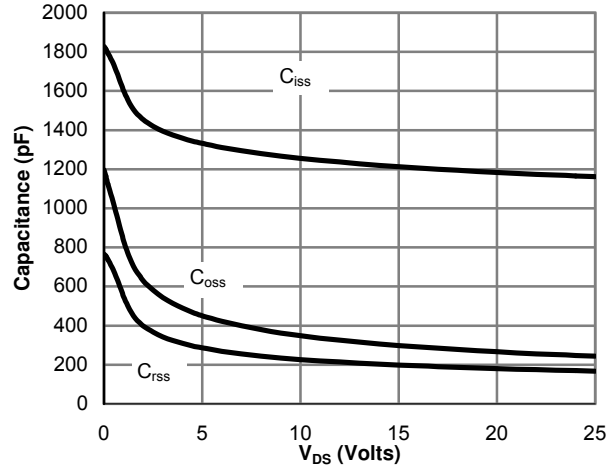


Figure 8: Capacitance Characteristics

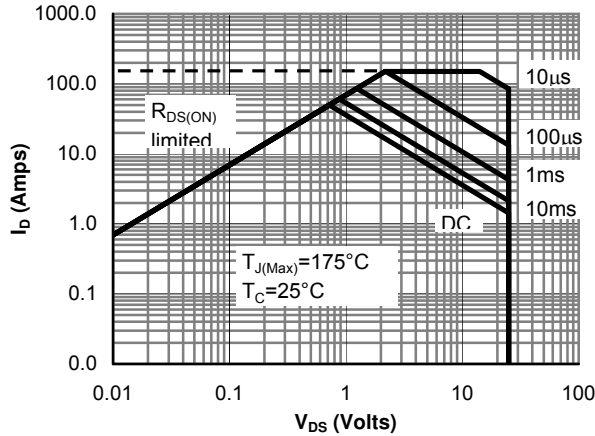


Figure 9: Maximum Forward Biased Safe Operating Area (Note F)

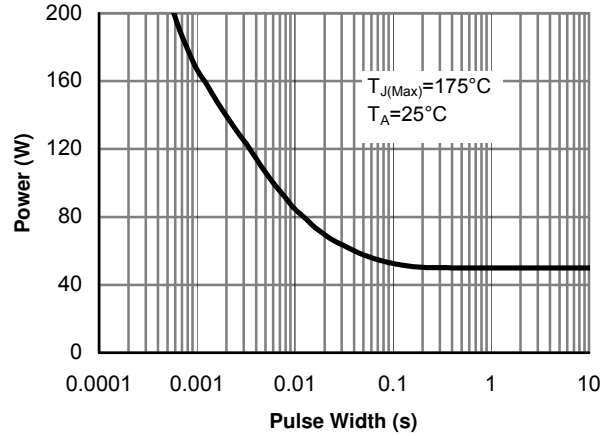


Figure 10: Single Pulse Power Rating Junction-to-Case (Note F)

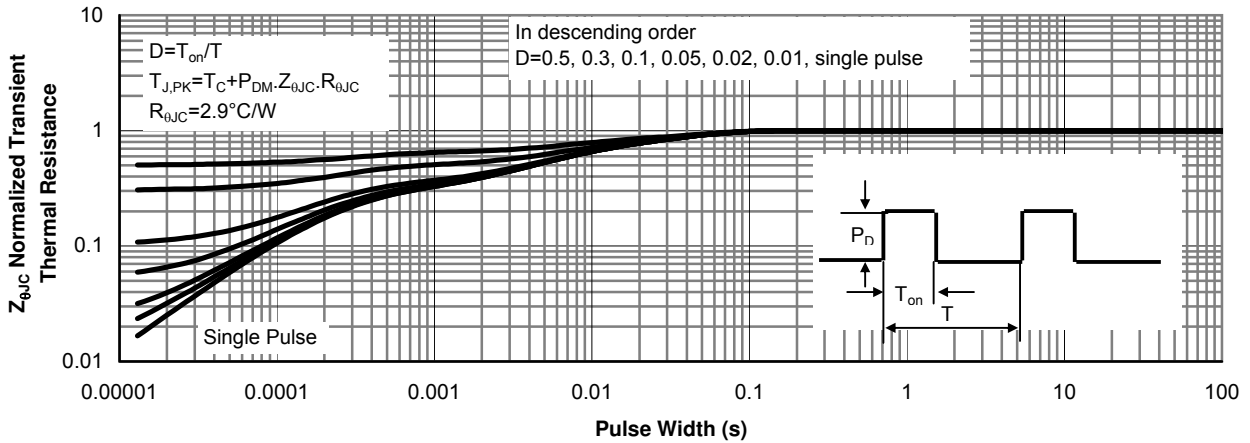


Figure 11: Normalized Maximum Transient Thermal Impedance (Note F)

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

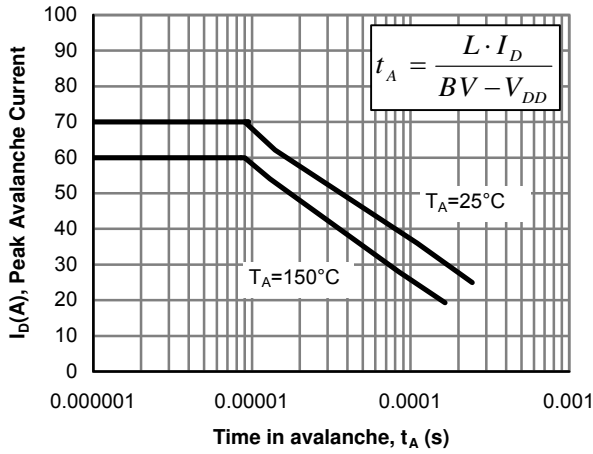


Figure 12: Single Pulse Avalanche capability

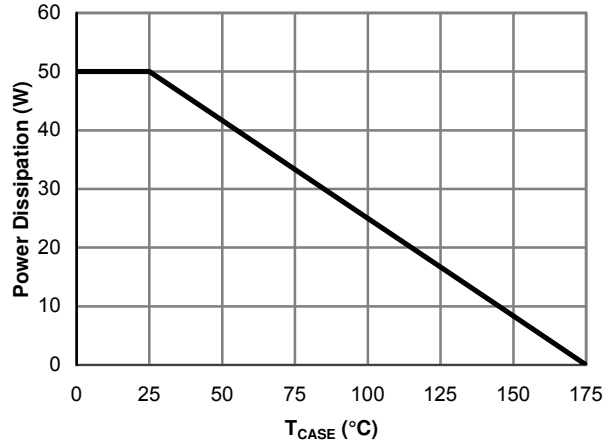


Figure 13: Power De-rating (Note B)

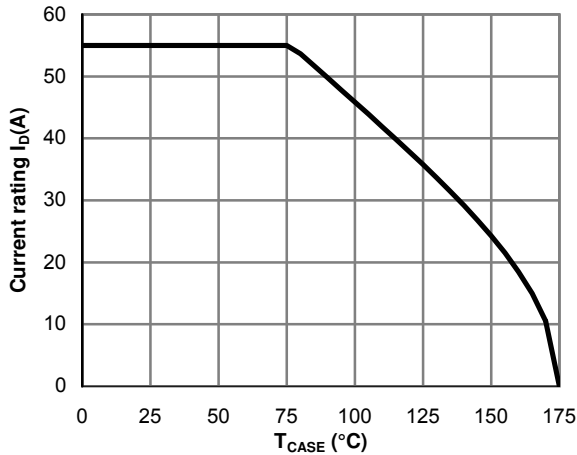


Figure 14: Current De-rating (Note B)

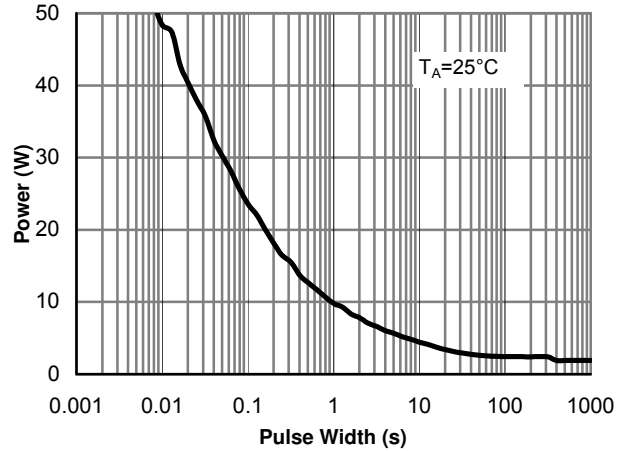


Figure 15: Single Pulse Power Rating Junction-to-Ambient (Note H)

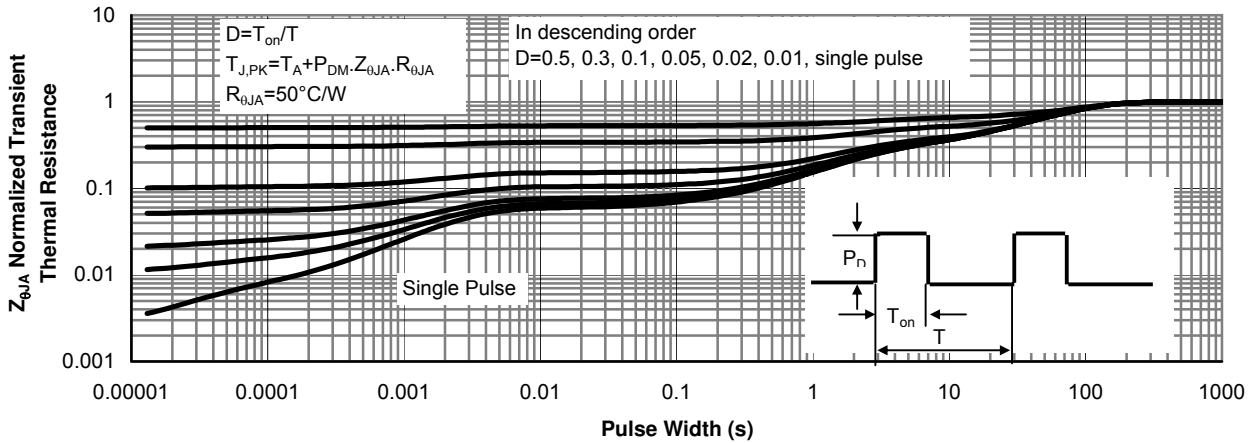


Figure 16: Normalized Maximum Transient Thermal Impedance (Note H)